

Errata to MPC885 PowerQUICC™ Reference Manual, Rev. 2

This document describes corrections to the *MPC885 PowerQUICC™ User's Manual*, Rev. 2. For convenience, the chapter number and page number of each erratum are provided. Items in bold are new since the last revision of this document.

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- General erratum Replace all instances of the term ‘60x’ with ‘external.’
- 10.4.1, 10-4 In Figure 10-2, “Internal Memory Map Register (MMR),” change “PARTNUM” reset from “000_0000” to “0000_1001” or “0x09”.
- 10.4.1, 10-4 In Figure 10-2, “Internal Memory Map Register (MMR)” and Table 10-2, “MMR Field Descriptions,” change bits 0–15 for ISB to 0–13. Bits 14 and 15 are reserved bits and are restricted to containing only a value of 0 to prevent conflicts between the Internal Memory Map and the SEC's memory map.
- 12.1.2, 12-22 In Table 12-1, “MPC885/MPC880 Signal Descriptions,” add RMII_MII_MDIO to name column of pin P19.
- 12.1.2, 12-23 In Table 12-1, “MPC885/MPC880 Signal Descriptions,” add RMII2-TXEN [pin T6] description to MII1-TXEN [pin T5] description
- 14.2.1, 14-4** In Table 14-1, “The Input Frequency Requirements,” change “320 MHz” to “400 MHz” as follows:

Table 14-1. The Input Frequency Requirements

MODCK[1-2]	Frequency In	PDF	MFI, MFN, MFD for DPGDCK
00, 01	OSCM = 10 MHz to 10.66 MHz	0	$160 \text{ MHz} < \text{OSCLK} * 2 * (\text{MFI} + (\text{MFN} / (\text{MFD} + 1))) < 400 \text{ MHz}$
11	EXTCLK = 10 MHz to 10.66 MHz	0	$160 \text{ MHz} < \text{OSCLK} * 2 * (\text{MFI} + (\text{MFN} / (\text{MFD} + 1))) < 400 \text{ MHz}$
10	$45 \text{ MHz} \leq \text{EXTCLK} \leq 66 \text{ MHz}$	$10 \text{ MHz} \leq \text{EXTCLK} / (\text{PDF} + 1) \leq 32 \text{ MHz}$	$160 \text{ MHz} < \text{OSCLK} * 2 * (\text{MFI} + (\text{MFN} / (\text{MFD} + 1))) / (\text{PDF} + 1) < 400 \text{ MHz}$

- 14.3.1.3, 14-13 In the first bullet note dealing with internal clock of 2 x EXTCLK, add the following: “assuming EXTCLK is between 50 MHz to 80 MHz”.
- 14.4.3, 14-17 In the description, “An inductor value of 8.2 Mhz and bypass capacitor values of 0.1 μF and 10 μF provide a two-pole filter with a cutoff frequency of 500 Hz”, change “8.2 MHz” to “8.2 mH”.
- 14.6.2, 14-21 In Figure 14-13, “PLL and Reset Control Register (PLPRCR),” change ‘0000’ under field PDF to ‘—’ because PDF is not affected by HRESET.
- 14.6.2, 14-22 In Figure 14-13, “PLL and Reset Control Register (PLPRCR),” and Table 14-9, “PLPRCR Field Descriptions,” change bit field “FIOPD” to “RESERVED”.
- 18.6.1, 18-6 In Table 18-4, “RCCR Field Descriptions,” change bit 12 description to say:
 “EIE. External interrupt enable. Configure as instructed in the download process of a Motorola-supplied RAM microcode package.
 0 DREQ0 cannot interrupt the CP.
 1 DREQ0 will interrupt the CP. This bit must be set to enable USB host SOF generation.”
- 19.1.2, 19-3 In Table 19-1, “U-Bus Arbitration IDs,” change the term ‘G2 Core’ to ‘PTEC Core’.

Section, Page No.	Changes
27.1, 27-2	In Figure 27-2, “Ethernet Block Diagram,” Clock Generator block: Internal Clock[s] arrows should be reversed; pointing <i>into</i> the block, and RCLK and TCLK arrows should be reversed; pointing <i>out</i> of the block
31.7.1, 31-9	In Figure 31-5, “USB Controller Operating Modes,” the arrow on the bottom of “Preamble” should point in the opposite direction.
31.7.2, 31-11	In Figure 31-6, “SOF Generation, the “dreq0” signal should point in the opposite direction.
31.7.2, 31-11	In the last paragraph, please change to: DREQ0 should be configured as external interrupt—bit EIE should be set to 1 in RCCR. When there are no hardware originated requests to the CP, it enters stall state. Configuring DREQ0 as an external interrupt request ensures that only a hardware interrupt request can wake up the host controller.
32.4.3, 32-7	In Table 32-3, “I2BRG Field Descriptions,” change the description for bits 0–7 to read as follows: “Division ratio 0–7. Specifies the divide ratio of the BRG divider in the I ² C clock generator. The output of the prescaler is divided by $2 \times (\text{DIV} + 3 + (2 \times \text{FLT}))$, and the clock has a 50% duty cycle. The FLT bit is in the I2MOD register. The minimum value for DIV is 3 if the digital filter is disabled (FLT = 0) and 6 if the digital filter is enabled (FLT = 1).”
33.8/33-19	Add a note to beginning of section, as follows: “PIP in transparent mode is not supported.”
35.2.1, 35-3	First bullet should reference SPS = 0 and second bullet should reference SPS = 1.
42.2.2, 42-3	Add the following note below the second paragraph:
NOTE	
The actual number of active PHY address signals is selected in UTMODE [ADDPIN]; see Section 43.2, “UTOPIA Mode Register (UTMODE).” When a PHY address signal is not activated, the pin reverts to its function as defined by PBDIR alone (UT becomes a don't care). For example, assuming that the UTOPIA interface has been initialized properly, and if only seven PHYs are used in a UTOPIA master application, the SMC1 data signals are still available because RxAddr [3] and TxAddr [3] are not active.	
45.2.1, 45-3	In Table 45-2, “MII and RMII Signals,” add ‘(input)’ next to the signal descriptions ‘Transmit Clock’ and ‘Receive Clock’.
45.2.5, 45-7	In Figure 45-2, “Ethernet Address Recognition Flowchart,” the promiscuous mode check at the bottom should indicate when R_CNTRL[PROM] = 0, the state machine leads to False.
45.3.1, 45-12	Add the following note below Table 45-6, “CPTR RMII Related Field Descriptions:”

NOTE

If auto-negotiation is used, then it is recommended to configure RMIIx_RATE_FECx after the PHY has finished the auto-negotiation. The user can then read the line speed from the PHY status registers using MII management frames, and then configure RMIIx_RATE_FECx accordingly.

- 45.3.2.13, 45-23 In Figure 45-17, “MII_DATA Register,” remove address offset(s) for FEC_2, 0x1E80 and 0x1E82.
- 45.3.2.13, 45-24 In the last paragraph, add the following: “In the MPC88x or MPC87x, all MII management interface transactions must be done through FEC1 registers. This includes MII_SPEED and MII_DATA registers.”
- 45.3.2.14, 45-24 In Figure 45-18, “MII_SPEED Field Descriptions,” remove address offset(s) for FEC_2, 0x1E84 and 0x1E86.
- Appendix F, F-1 Under the first bullet, remove the sentence, “The time-slot assigner is not implemented.”

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